

P-Channel 20V (D-S)MOSFET

General Description

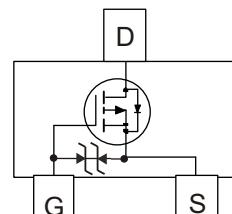
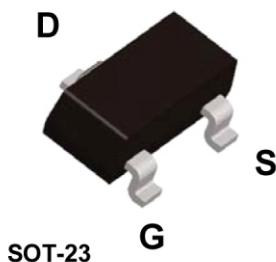
This miniature surface mount MOSFET uses advanced Trench process, low $R_{DS(on)}$ assures minimal power loss and energy convert, which makes this device ideal for use in power management circuit.

Features

- $V_{DS}(V) = -20V$
- $I_D(A) = -3.6A(V_{GS} = -4.5V)$
- $R_{DS(on)} = 70\ m\Omega @ V_{GS} = -4.5V$
- $R_{DS(on)} = 110\ m\Omega @ V_{GS} = -2.5V$
- $R_{DS(on)} = 250\ m\Omega @ V_{GS} = -1.8V$
- ESD Rating : 3000V HBM
- Low gate charge
- Fast switching speed
- High performance trench technology

Applications

- Load switching
- Low current DC-DC converters
- Small power management



Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current ^a	I_D	-3.6	A
		-2.8	
Pulsed Drain Current ^b	I_{DM}	-14	
Continuous Source Current (Diode Conduction) ^a	I_S	-2.3	A
Power Dissipation ^a	P_D	1.4	W
		0.9	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Resistance Ratings

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$R_{\theta JA}$	90	°C/W
		130	



Package Outlines and Ordering Information

Device	Device Marking	Reel Size	Tape Width	Quantity
MI3473	M04S	7"	8mm	3000 units

Specifications (TA = 25°C Unless Otherwise Noted)

Parameter	Symbol	Test Conditions	Limits			Units
			Min	Typ	Max	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	-20			V
Gate-Threshold Voltage	V _{GS(th)}	V _D =V _{GS} , I _D = -250 uA	-0. 5	-0. 75	-1	
Gate-Body Leakage	I _{GSS}	V _D =0V, V _{GS} =±12V			±10	uA
Zero Gate Voltage Drain Current	I _{DSS}	V _D =-20V, V _{GS} =0V			-1	uA
		V _D =-20V, V _{GS} =0V, T _J =85°C			-30	
On-State Drain Current ^c	I _{D(on)}	V _D =-5V, V _{GS} =-4. 5V	-14			A
Drain-Source On-Resistance ^c	R _{D(S(on))}	V _{GS} =-4.5V, I _D =-3.6A		55	70	mΩ
		V _{GS} =-2.5 V, I _D =-2A		80	110	
		V _{GS} =-1.8 V, I _D =-1A		135	250	
Forward Tranconductance ^c	g _{fs}	V _D =-5V, I _D =-3.6A		11		S
Diode Forward Voltage	V _{SD}	I _S =-1. 2A, V _{GS} =0V		-0.7	-1. 1	V
Dynamic						
Input Capacitance	C _{iss}	V _D =-10V, V _{GS} =0V f=1MHz		550		pF
Output Capacitance	C _{oss}			90		
Reverse Transfer Capacitance	C _{rss}			80		
Switching						
Total Gate Charge	Q _g	V _D =-10V, V _{GS} =-4.5V I _D =-3.6A		6.2	9	nC
Gate-Source Charge	Q _{gs}			1.3		
Gate-Drain Charge	Q _{gd}			1.2		
Turn-On Delay Time	t _{d(on)}	V _D =-10V, I _D =-2.2A, R _G =6 ohm, V _{GEN} =-4.5V		5	8	ns
Rise Time	t _r			12	24	
Turn-Off Delay Time	t _{d(off)}			30	65	
Fall-Time	t _f			22	37	

Notes: a. Surface Mounted on 1" x 1" FR4 Board.
 b. Pulse width limited by maximum junction temperature
 c. Pulse test: PW <= 300us duty cycle <= 2%.



Typical Electrical and Thermal Characteristics

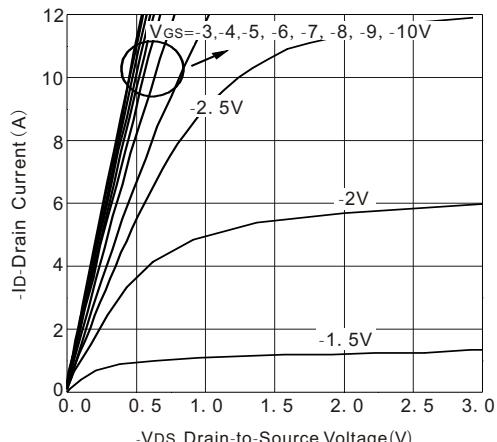


Figure 1: Output Characteristics

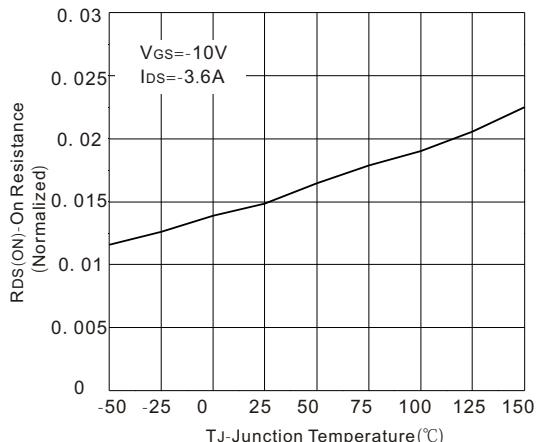


Figure 2: On-Resistance vs. Junction Temperature

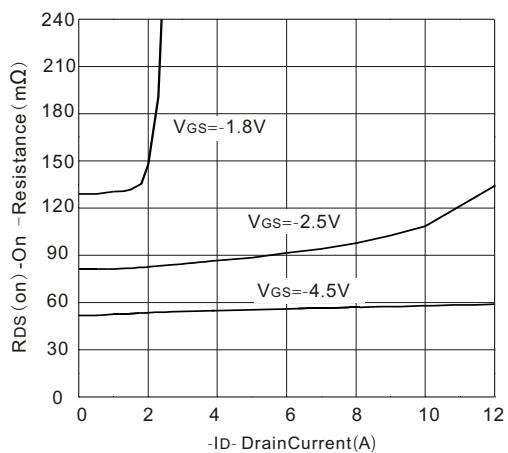


Figure 3: On-Resistance vs. Drain Current

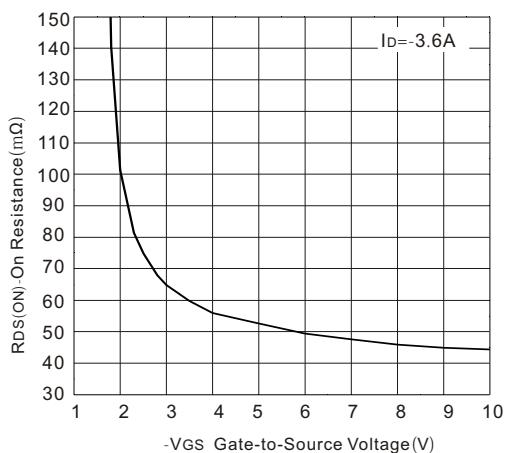


Figure 4: On-Resistance vs. Gate-to-Source Voltage

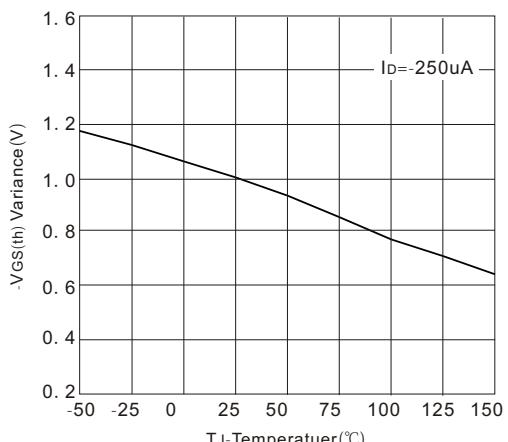


Figure 5: Threshold Voltage

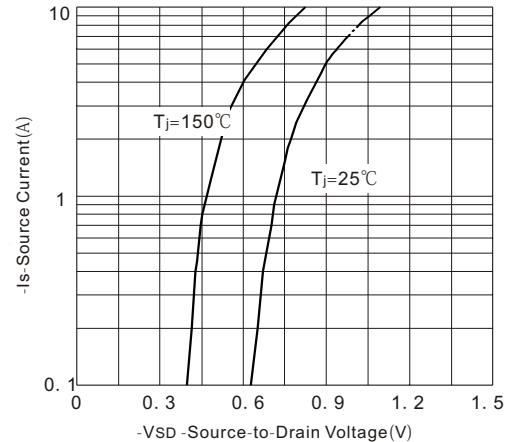
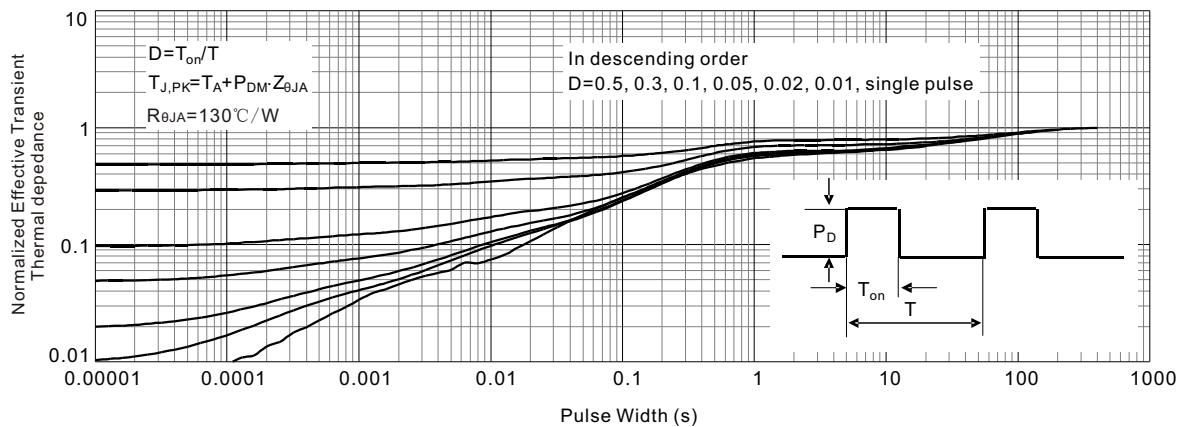
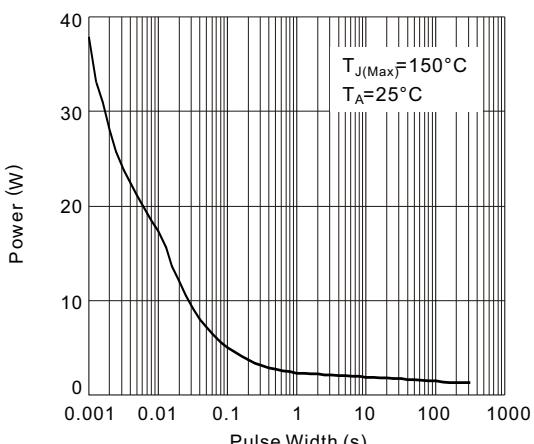
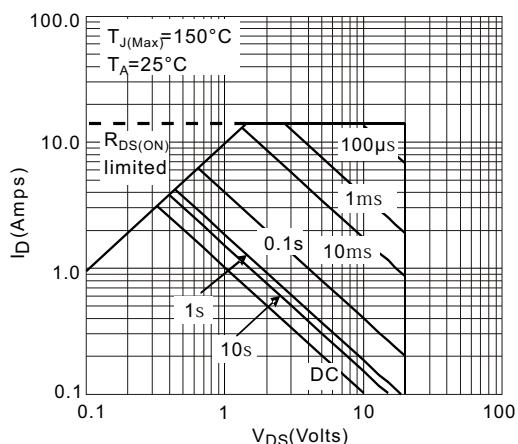
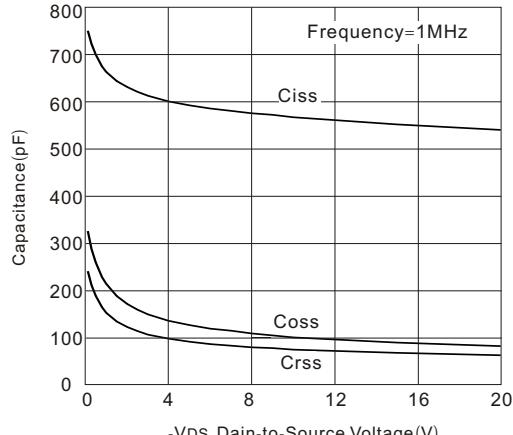
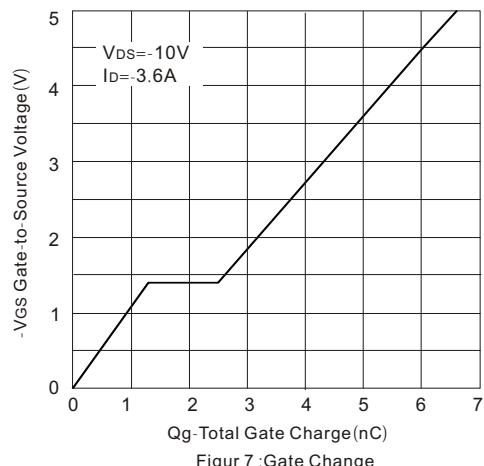


Figure 6: Source-Drain Diode Forward Voltage



Typical Electrical and Thermal Characteristics

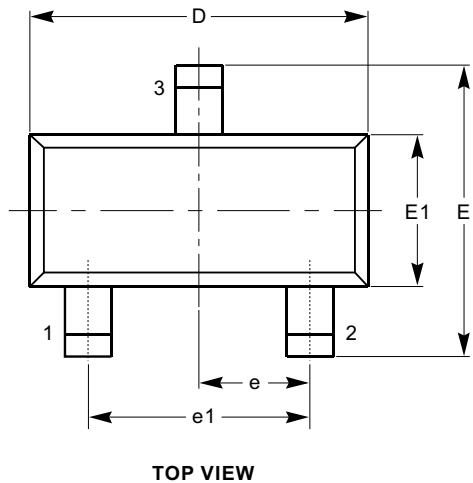


Note d: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

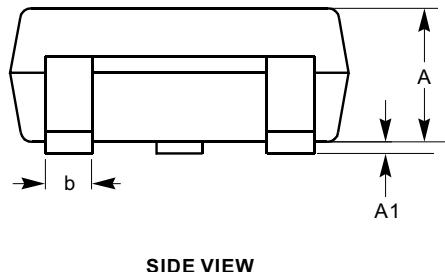


Package

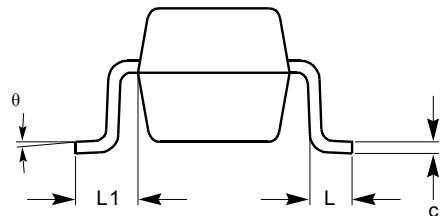
SOT -23 3-Lead



SYMBOL	MIN	NOM	MAX
A	0.70	1.00	1.15
A1	0.00		0.13
b	0.30	0.40	0.50
c	0.08	0.13	0.20
D	2.80	2.90	3.10
E	2.60	2.80	3.00
E1	1.40	1.60	1.80
e		0.95 BSC	
e1		1.90 BSC	
L		0.400 REF	
L1		0.540 REF	
θ	0°	5°	8°



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC TO-236.

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